

LTM8055 121LD-BGA-PBF 15mm X 15mm X 4.92mm (TABLE OF MATERIAL DECLARATION)

The LTM8055 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2761	Barium Compounds	7727-43-7	0.00701	2.54
				Bismaleimide/Triazine/Resin/Filler Substance(Silica Crystalline)	105391-33-1,1156-51-0/9003-36-5/21645-51-2	0.05313	19.24
				Copper Metal	7440-50-8	0.15536	56.26
				Copper Compounds	147-14-8	0.00006	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00003	0.01
				Gold metal or alloy	7440-57-5	0.00052	0.19
				Nickel	7440-02-0	0.00243	0.88
				Zinc	7440-66-6	0.00030	0.11
				Continuous Filament Fiber Glass	65997-17-3	0.04172	15.11
				Acrylic Resin	non-disclosure	0.01337	4.84
				Epoxy Resin	non-disclosure	0.00005	0.02
				Chromium(III) Oxide	1308-38-9	0.00001	0.00
				Silica amorphous	7631-86-9	0.00014	0.05
				Talc;not containing fibers like asbestos	14807-96-9	0.00080	0.29
				Aromatic Carbonyl compounds	non-disclosure	0.00077	0.28
				Cyanoguanidine	461-58-5	0.00002	0.01
				Calcium caobonate	471-34-1	0.00001	0.00
				Amine compounds	non-disclosure	0.00010	0.04
				Leveling agent and others	non-disclosure	0.00030	0.11
2	Solder Paste	Alloy	0.0383	Sn	7440-31-5	0.03641	95.00
				Sb	7440-36-0	0.00192	5.00
3	Passive/Active Components		0.8372	Iron Powder (Fe)	7439-89-6	0.64146	76.62
				Copper (Cu)	7440-50-8	0.16340	19.52
				Nickel (Ni)	7440-02-0	0.00393	0.47
				Tin (Sn)	7440-31-5	0.00585	0.70
				Ceramic (Ba) Compounds	12047-27-7	0.02256	2.69
4	Active Ics	Silicon	0.0077	Silicon	7440-21-3	0.00766	100.00
5	Wire	Gold	0.0008	Au	7440-57-5	0.00083	99.99
6	Solder Ball	SAC305	0.2023	Sn	7440-31-5	0.19523	96.50
				Ag	7440-22-4	0.00607	3.00
				Cu	7440-50-8	0.00101	0.50
7	Encapsulation	Epoxy Resin	1.7126	Fused Silica	60676-86-0	1.32216	77.20
				Epoxy Resin	non-disclosure	0.15243	8.90
				Phenol Resin	non-disclosure	0.15243	8.90
				Crytalline Silica	14808-60-7	0.05138	3.00
				Carbon Black	1333-86-4	0.00856	0.50
				Metal Hydroxide	non-disclosure	0.02569	1.50
Total Package Weight			3.0751				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts